ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® Material Comp © Copyright 2005. Il international and Par	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docum level parts, t	ent is a declara	ation of the encompass	substances es all lowe	s within the er level mat	manufacture erials for wh	er listed ite nich the ma	m. Note: nufacture	if the item is an as r has engineering	sembly with lowe responsibility.
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					eous Materia	als and Mfg Information			
Supplier Information														
Company name* Compa			ompany unique ID			Unique ID Authority					Response Date*			
onsemi										2025-07-16				
Contact Name	tact Name Title - Contact				Phone - Contact*						Email - Contact*			
Product-Env-Stewards Product Env			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Rep			presentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Prod			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com			
Requester Item Number	em Number Mfr Item Nu		Number Mfr Item Name			Effective Da	te Versior	ı	Manufacturing Site		W	eight*	UOM	Unit Type
	SZMMS	ZMMSZ5241BT1G ZEN SOD		0123 REG 0.5W 11V		2025-07-16			CN1		11	.67	mg	Each
Manufacturing Proccess Information	tion										<u>i</u>			
Terminal Plating / Grid Array Ma	aterial Terminal Base All		Alloy	J-STD-020 MSL Rating		Peak Pro	A Process Body Temperature Max Time		me at Peak '	ak Temperature Number of Reflow Cycles		eles		
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		second	3 3		
Comments														
evel 1 - maximum time at peak temperatu	re during so	ldering is 10-3	0 seconds											
for more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.88	mg	Supplier	Silicon (Si)	7440-21-3		0.88	mg	
Lead Frame	3.19	mg	В	Nickel (Ni)	7440-02-0		1.158	mg	
			Supplier	Iron (Fe)	7439-89-6		1.6014	mg	
			Supplier	Copper (Cu)	7440-50-8		0.4306	mg	
Mold Compound-Black	6.51	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.651	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0325	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.9439	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		4.2315	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.651	mg	
Plating	0.8	mg	Supplier	Tin (Sn)	7440-31-5		0.8	mg	
Wire Bond	0.29	mg	Supplier	Palladium (Pd)	7440-05-3		0.0038	mg	
			Supplier	Copper (Cu)	7440-50-8		0.2862	mg	